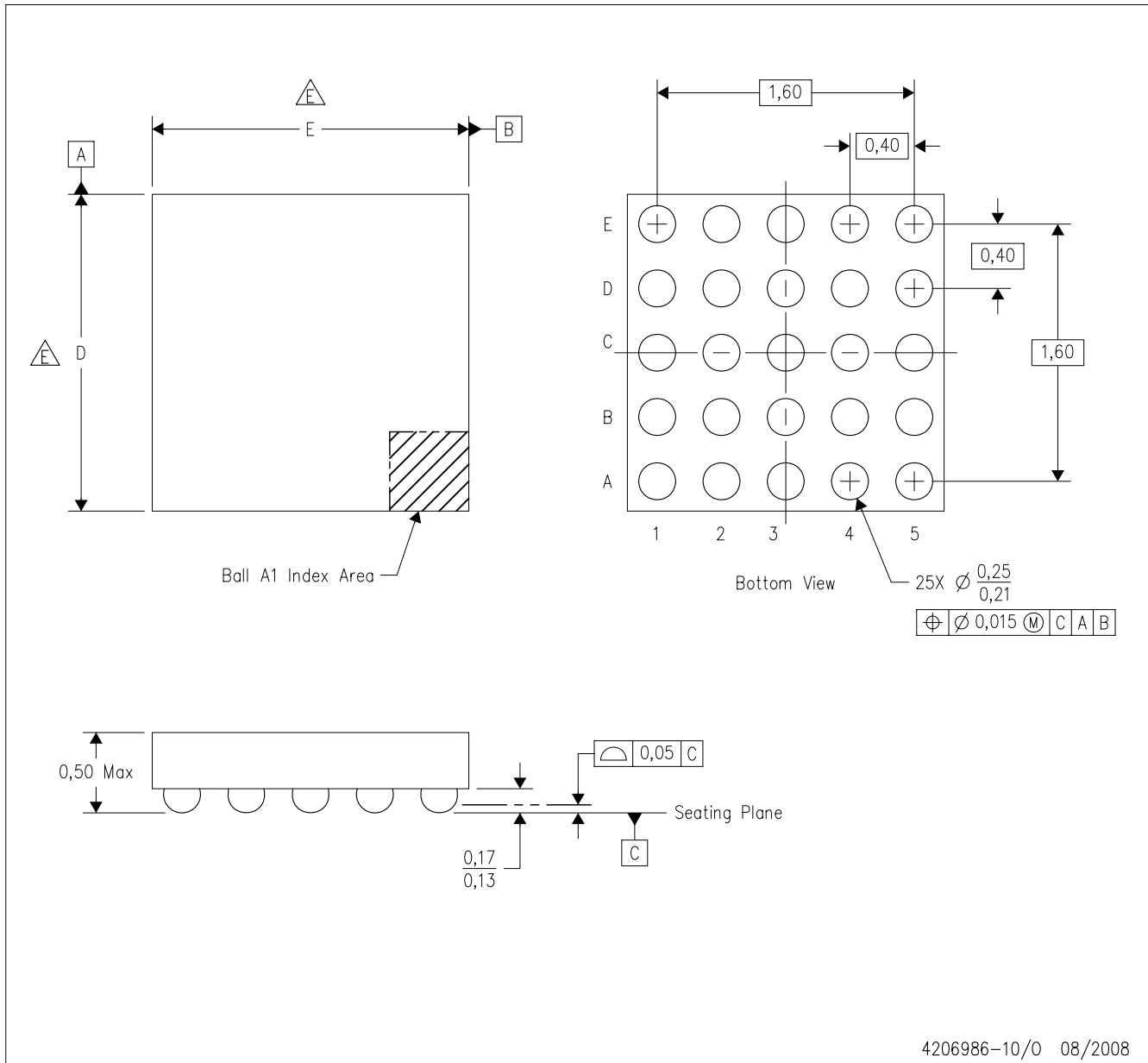


MECHANICAL DATA

YFP (S-XBGA-N25)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.
 - D. This is a Pb-free solder ball design.
 - Devices in this YFP package can have dimensions D and E ranging from 1.94 to 2.10. To determine the exact package size of a particular device, Refer to the device Data Sheet or contact a local TI representative.

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